

Abstract of the Disclosure

A semiconductor device includes pads formed on a semiconductor chip, conductive sections connected to the pads, respectively, conductive bumps on surfaces
5 of the conductive sections, and an insulating film covering the semiconductor chip other than the surfaces of the conductive sections. The insulating film including a stress buffering layer in a lateral direction of the conductive sections to relax a stress
10 applied to the bumps.

2025-03-04 14:00:00